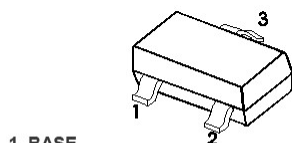


SOT-23


1. BASE

2. EMITTER

3. COLLECTOR

Marking: 2GM
特征 Features

- 最大功率耗散 225mW; Power Dissipation of 225mW
- 高稳定性和可靠性。High Stability and High Reliability

机械数据 Mechanical Data

- 封装: SOT-23 封装 SOT-23 Small Outline Plastic Package
- 环氧树脂 UL 易燃等级 Epoxy UL: 94V-0
- 安装位置: 任意 Mounting Position: Any

极限值和温度特性(TA = 25°C 除非另有规定)

Maximum Ratings & Thermal Characteristics (Ratings at 25°C ambient temperature unless otherwise specified.)

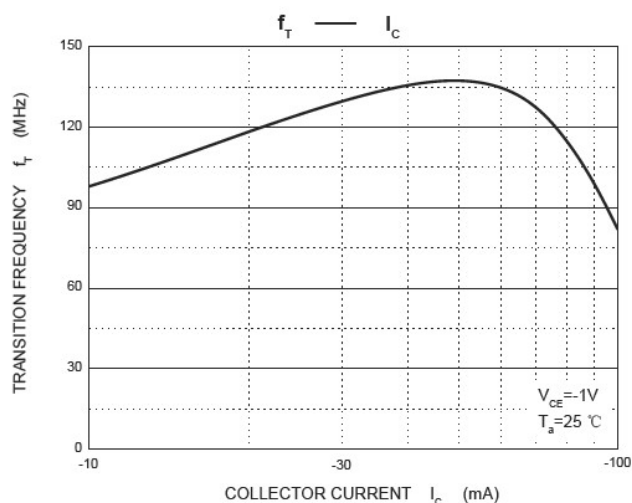
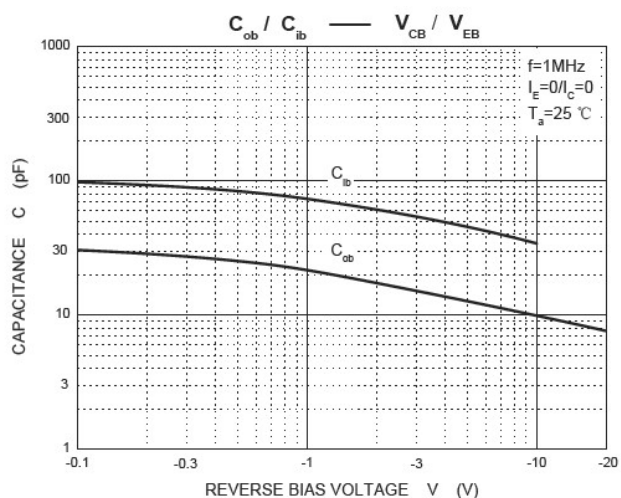
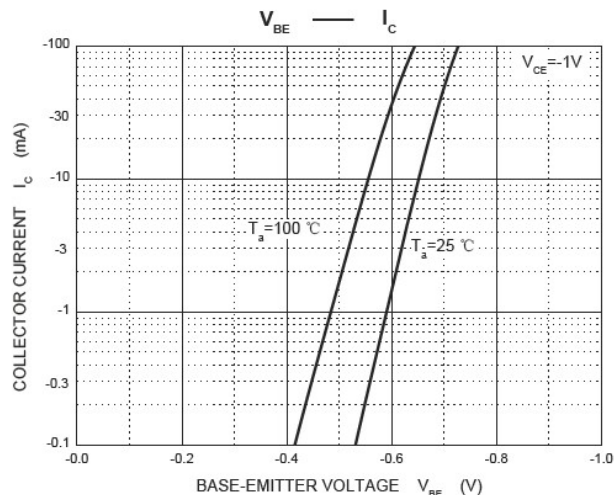
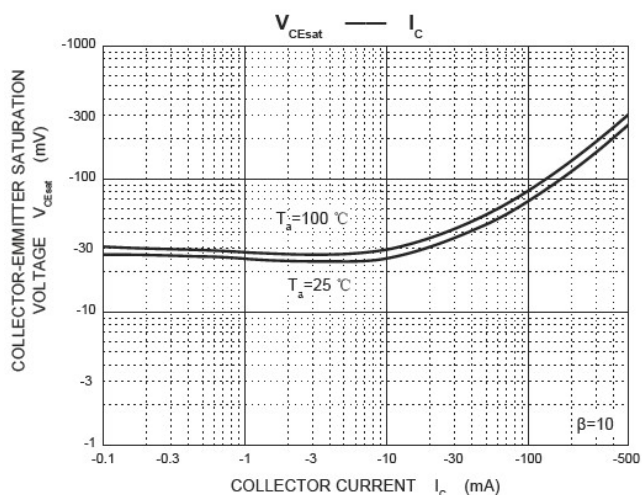
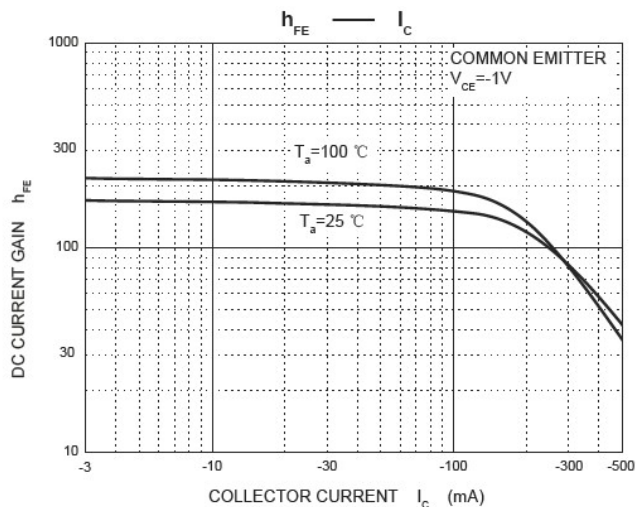
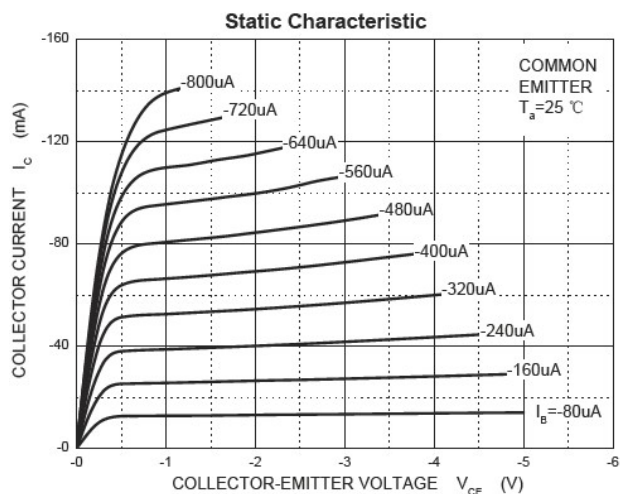
参数 Parameters	符号 Symbol	数值 Value	单位 Unit
Collector-Base Voltage	V _{CBO}	-80	V
Collector-Emitter Voltage	V _{CEO}	-80	V
Emitter -Base Voltage	V _{EBO}	-4	V
Collector Current-Continuous	I _C	-500	mA
Collector Power Dissipation	P _C	225	mW
Junction Temperature	T _j	150	°C
Storage Temperature	T _{stg}	-55-+150	°C
Thermal resistance From junction to ambient	R _{θJA}	555	°C/W

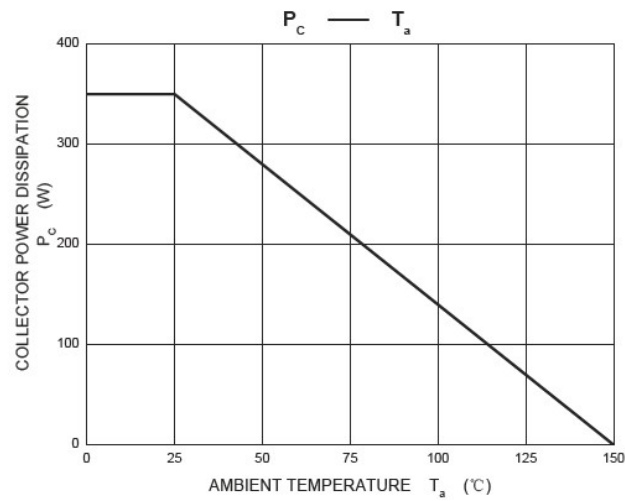
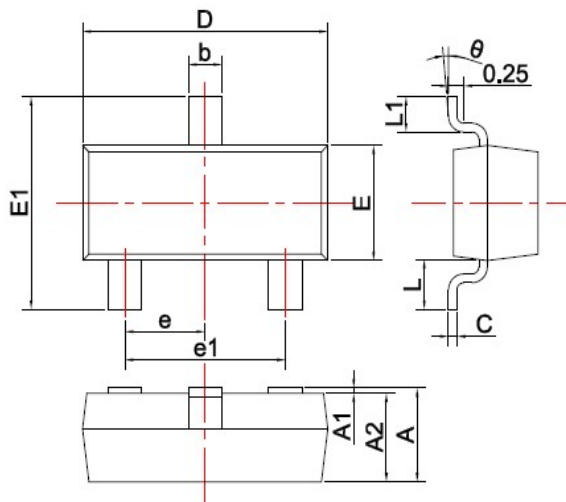
电特性 (TA = 25°C 除非另有规定)

Electrical Characteristics (Ratings at 25°C ambient temperature unless otherwise specified.)

参数 Parameter	符号 Symbols	测试条件 Test Condition	界限 Limits		单位 Unit
			Min	Max	
Collector-base breakdown voltage	V _{(BR)CBO}	I _C =-100uA, I _E =0	-80		V
Collector-emitter breakdown voltage	V _{(BR)CEO} *	I _C =-1mA, I _B =0	-80		V
Emitter-base breakdown voltage	V _{(BR)EBO}	I _E =-100uA, I _C =0	-4		V
Collector cut-off current	I _{CBO}	V _{CB} =-80V, I _E =0		-100	nA
Emitter cut-off current	I _{EBO}	V _{EB} =-4V, I _C =0		-100	nA
Collector cut-off current	I _{CEO}	V _{CE} =-60V, I _B =0		-1.0	uA
DC current gain	hFE(1) *	V _{CE} =-1V, I _C =-10mA	100	400	
	hFE(2) *	V _{CE} =-1V, I _C =-100mA	100		
Collector-emitter saturation voltage	V _{CE(sat)} *	I _C =-100mA, I _B =-10mA		-0.25	V
Base -emitter voltage	V _{BE}	V _{CE} =-1V, I _C =-100mA		-1.20	V
Transition frequency	f _T	V _{CE} =-1V, I _C =-100mA,f=100MHz	50		MHz

*Pulse test: pulse width ≤ 300us, duty cycle ≤ 2.0%

Typical characteristics


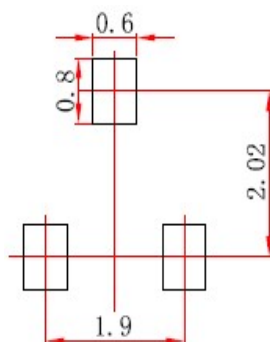

SOT-23 PACKAGE OUTLINE Plastic surface mounted package


SYMBOL	DIMENSIONS	
	MIN.	MAX.
A	0.900	1.150
A1	0.000	0.100
A2	0.900	1.050
b	0.300	0.500
c	0.080	0.150
D	2.800	3.000
E	1.200	1.400
E1	2.250	2.550
e	0.950TYP	
e1	1.800	2.000
L	0.550REF	
L1	0.300	0.500
θ	0 $^{\circ}$	8 $^{\circ}$

Unit: mm

焊盘设计参考Precautions: PCB Design

Recommended land dimensions for SOT-23 diode. Electrode patterns for PCBs


Note:

1. Controlling dimension: In millimeters.
2. General tolerance: $\pm 0.05\text{mm}$.
3. The pad layout is for reference purposes only.

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